

FIGURE 1B

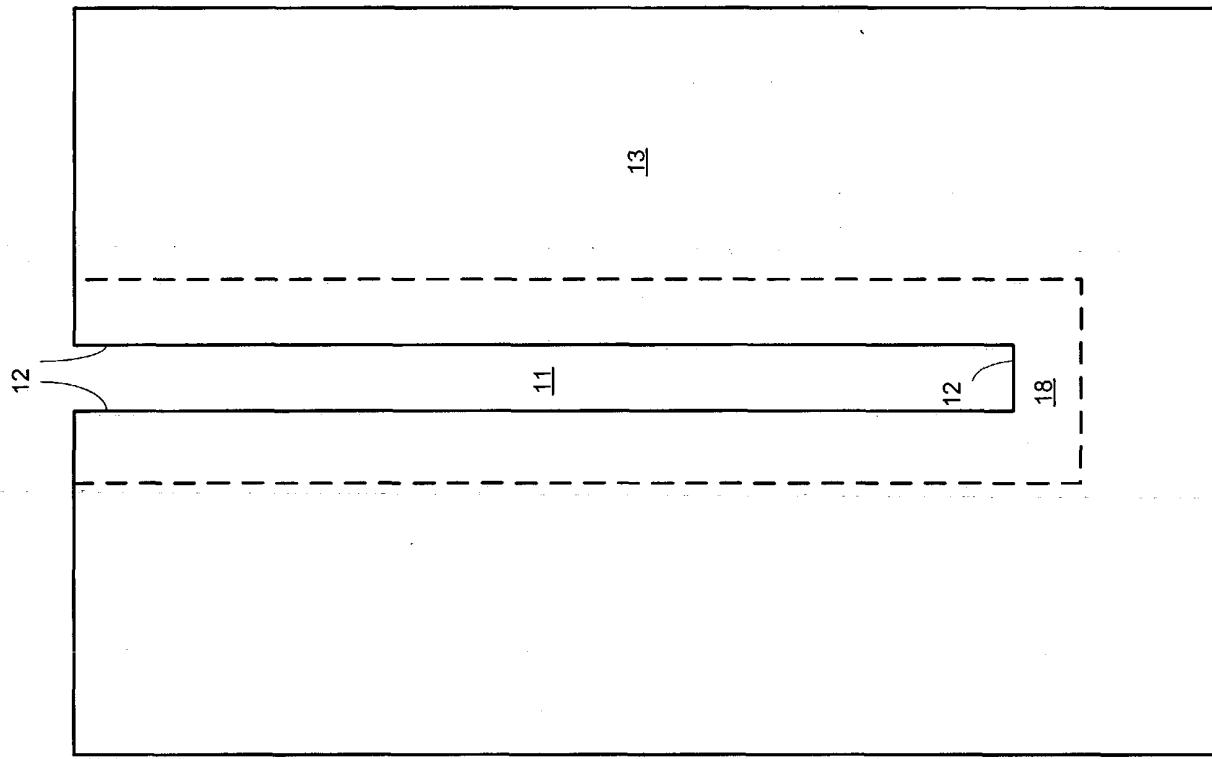


FIGURE 1A

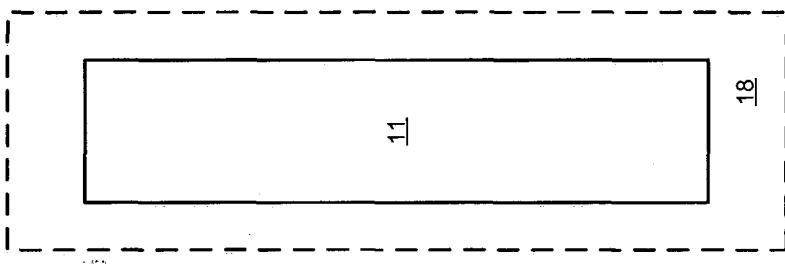


FIGURE 2B

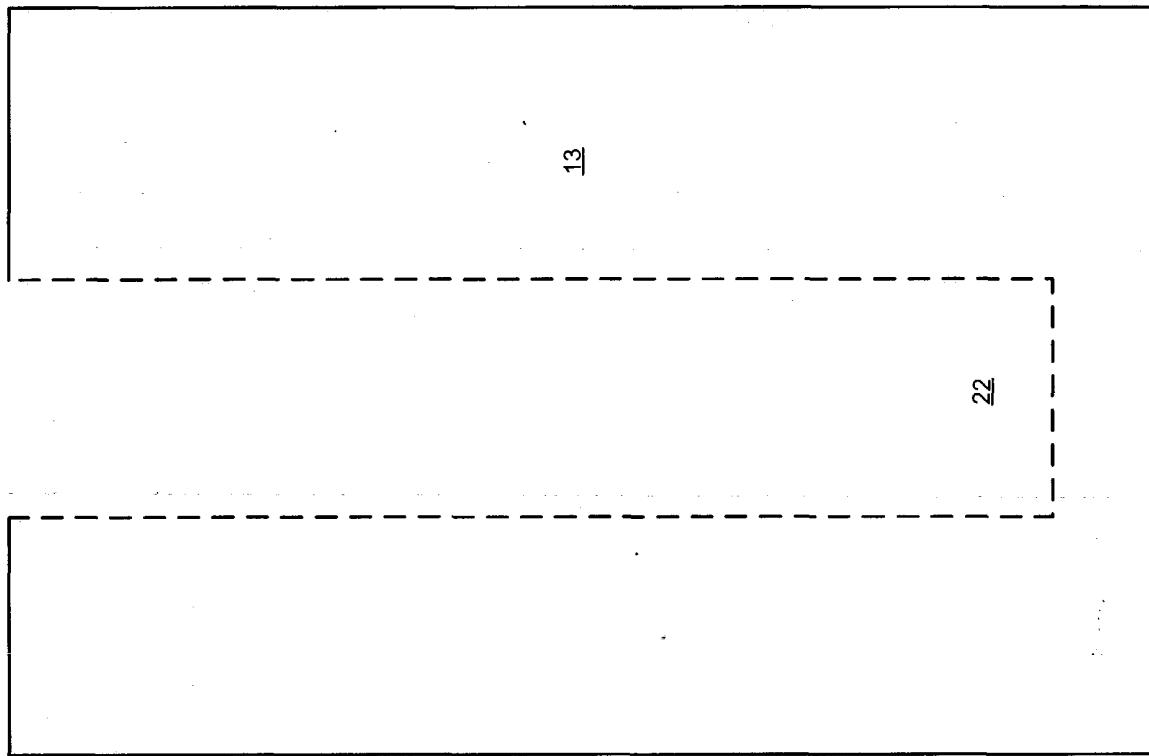
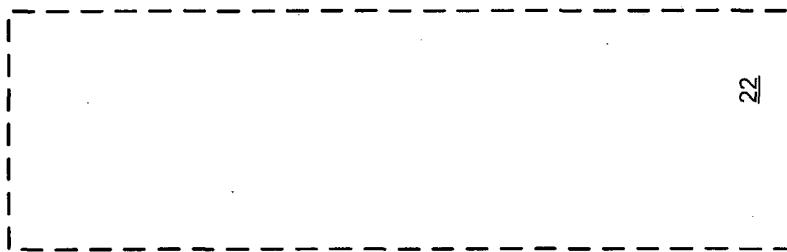


FIGURE 2A



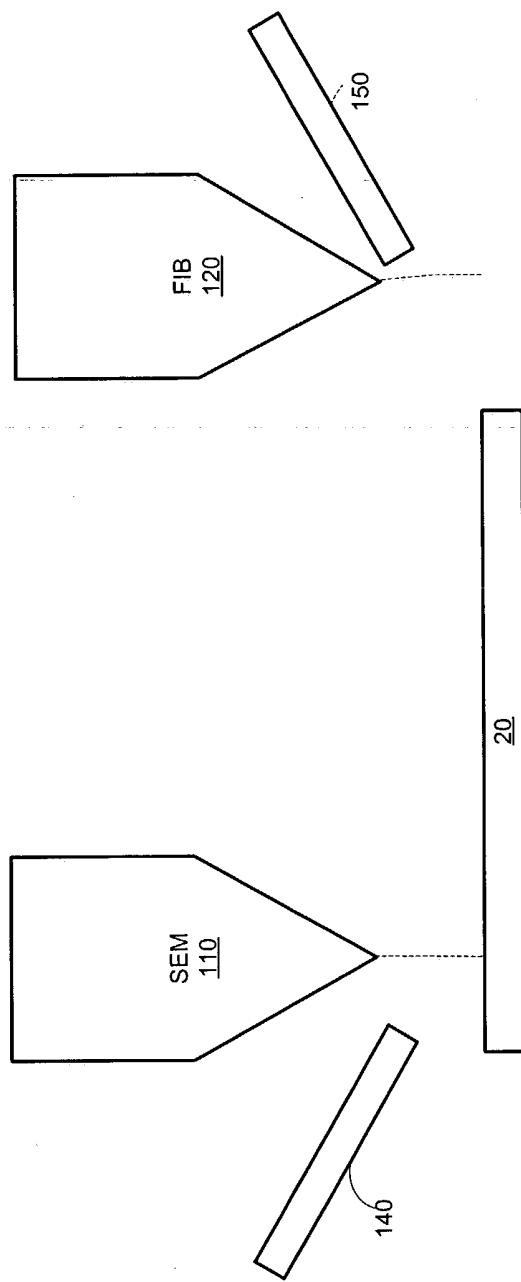


Figure 3

milling the integrated circuit by a fast contaminating milling process,  
thus introducing ion contamination

210

defining a suspected ion contaminated area

220

removing the suspected ion contaminated area by non-  
contaminating charged particle beam

230

200

FIGURE 4a

defining a suspected ion contaminated area  
310

removing the suspected ion contaminated area by non-  
contaminating charged particle beam.

320

300

FIGURE 4b